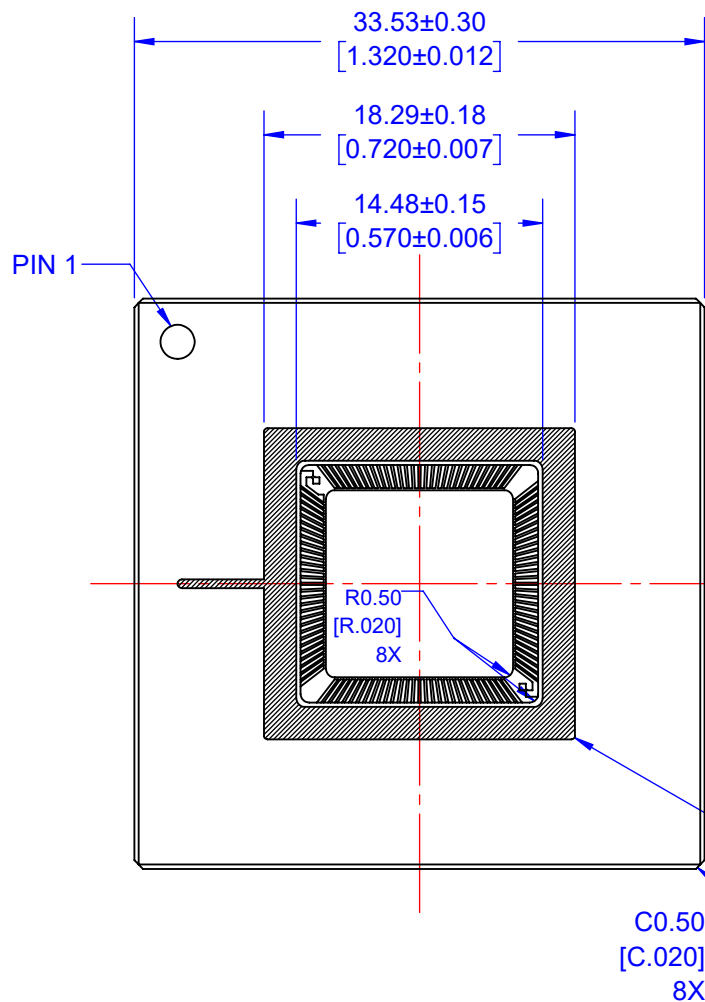
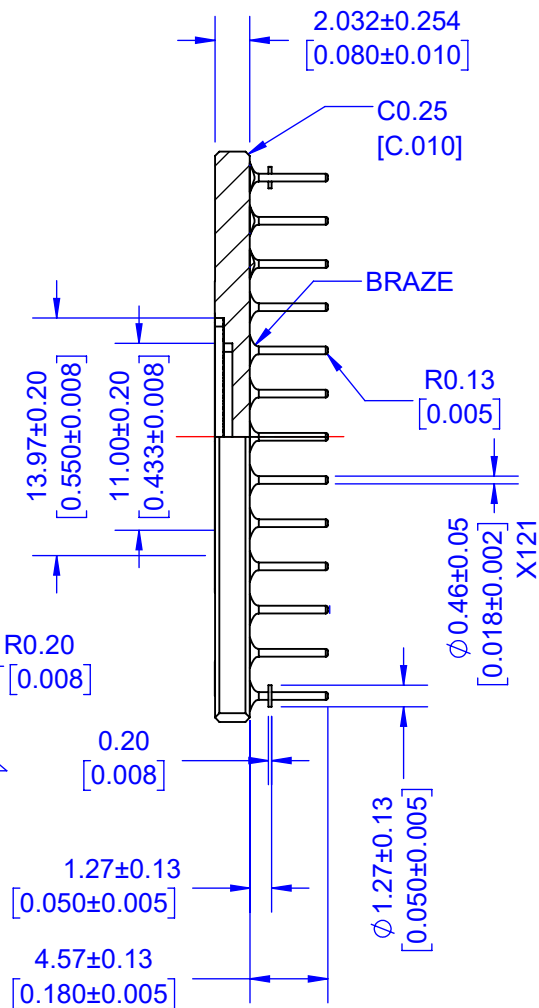


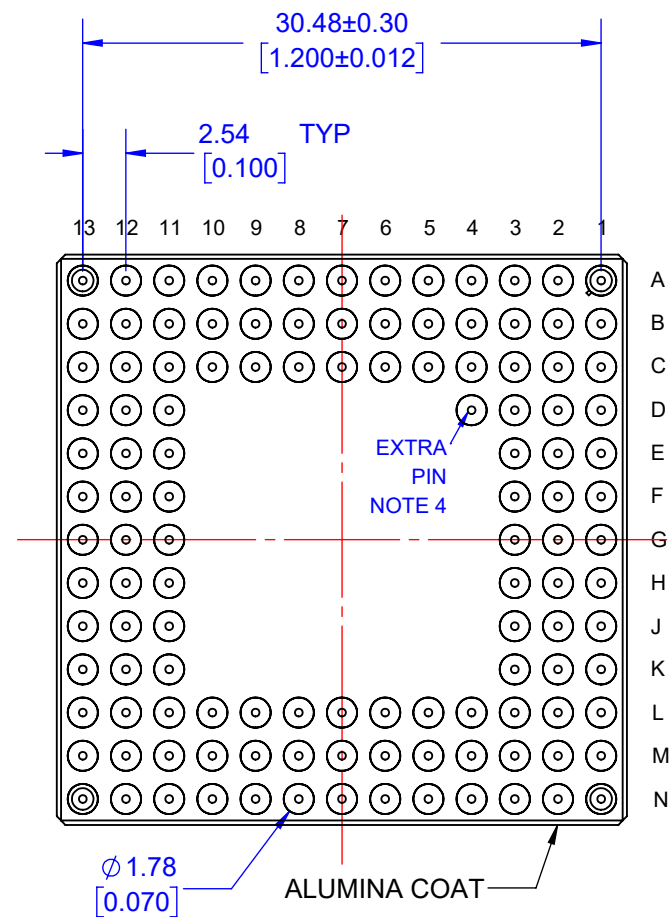
TOP VIEW



SIDE VIEW



BOTTOM VIEW

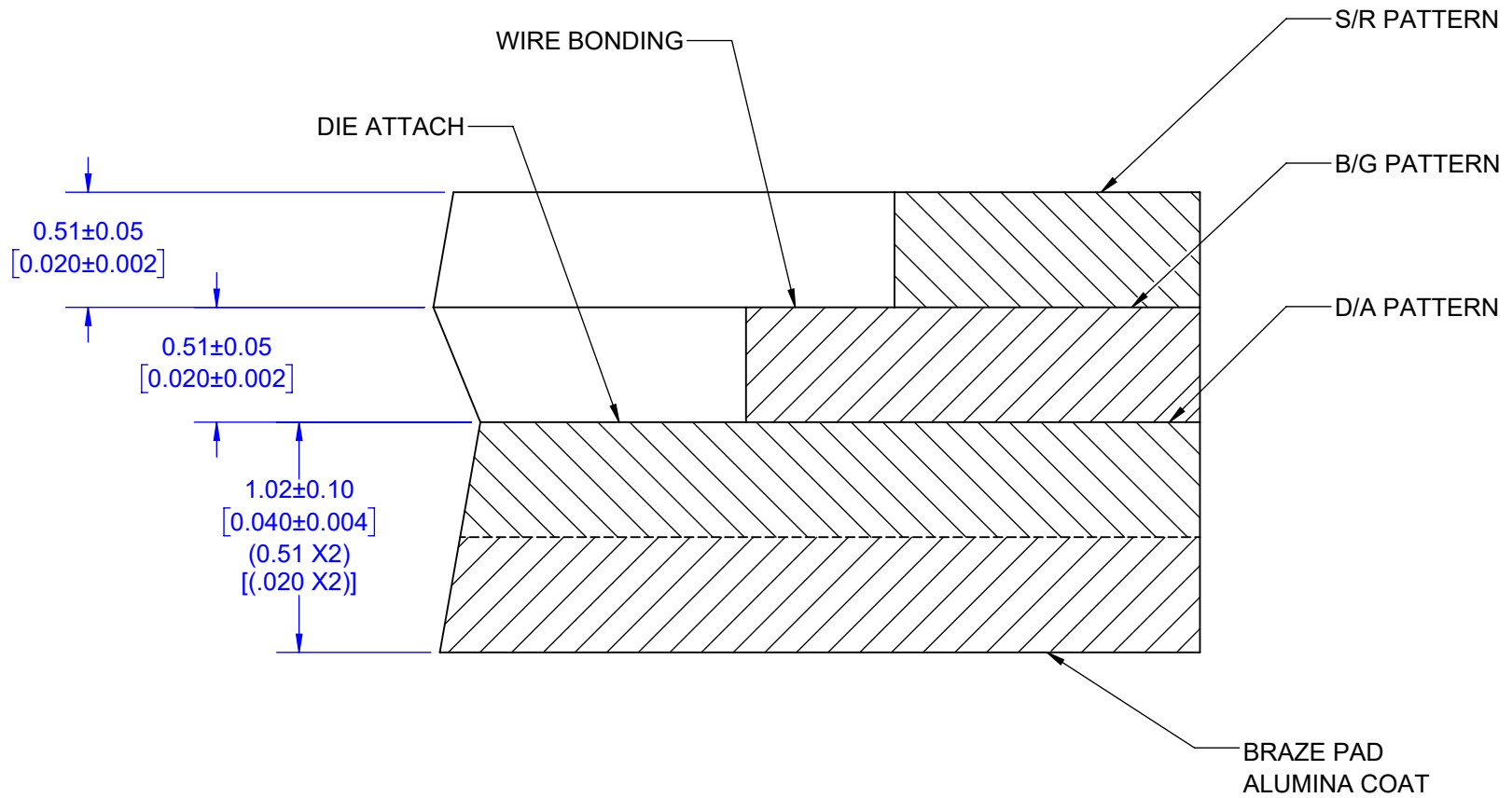


Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS mm [INCHES].
- 2) ALL EXPOSED METAL AND METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN. THK. OVER NICKEL PLATED. 50-350 MICRO-INCH.
- 3) DIE ATTACH AREA SHALL BE METALLIZED.
- 4) EXTRA PIN D4, S/R AND D/A ELECTRICALLY ISOLATED.
- 5) LEAD RESISTANCE: 800 Milli OHM MAXIMUM.

APPROVALS	DATE	TopLine®			
DRAWN T. Au	2/26/2022				
ENG M. Hart	2/26/2022	TITLE CPGA121T13x13-N433 CERAMIC PIN GRID ARRAY			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		2:1	A	161210	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 7
REVISED					

PACKAGE STACK UP



TopLine®

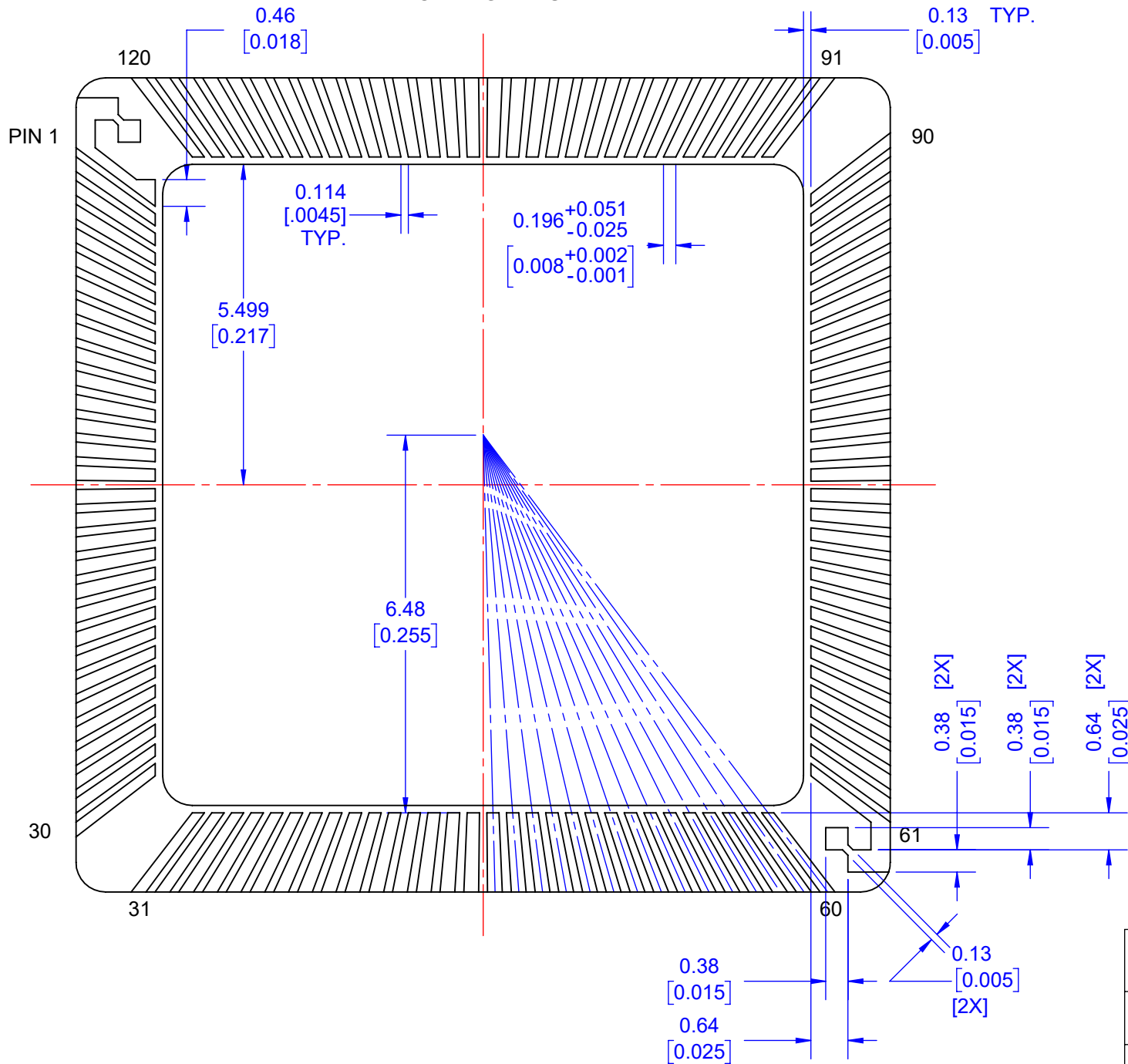
TITLE CPGA121T13x13-N433
CERAMIC PIN GRID ARRAY

SCALE	SIZE	DRAWING NO.	REV
32:1	A	161210	A

DO NOT SCALE DRAWING

SHEET 2 OF 7

BONDING PADS



W/B NO.	W/B ANGLE
46	1.370°
47	4.108°
48	6.840°
49	9.560°
50	12.261°
51	14.938°
52	17.585°
53	20.196°
54	22.767°
55	25.293°
56	27.770°
57	30.194°
58	32.562°
59	34.871°
60	37.119°

Table shows 1/8 of the total and is symmetrical to the center line.

TopLine®

TITLE CPGA121T13x13-N433
CERAMIC PIN GRID ARRAY

SCALE 10:1	SIZE A	DRAWING NO. 161210	REV A
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DO NOT SCALE DRAWING SHEET 3 OF 7

BOND PAD NET LIST

BOND	PIN	BOND	PIN	BOND	PIN	BOND	PIN	BOND	PIN
1	C3	26	L1	51	N9	76	G11	101	A9
2	B2	27	M1	52	M9	77	G13	102	C8
3	B1	28	K3	53	N10	78	F13	103	B8
4	D3	29	L2	54	L9	79	F12	104	A8
5	C2	30	N1	55	M10	80	F11	105	B7
6	C1	31	L3	56	N11	81	E13	106	C7
7	D2	32	M2	57	N12	82	E12	107	A7
8	E3	33	N2	58	L10	83	D13	108	A6
9	D1	34	L4	59	M11	84	E11	109	B6
10	E2	35	M3	60	N13	85	D12	110	C6
11	E1	36	N3	61	L11	86	C13	111	A5
12	F3	37	M4	62	M12	87	B13	112	B5
13	F2	38	L5	63	M13	88	D11	113	A4
14	F1	39	N4	64	K11	89	C12	114	C5
15	G2	40	M5	65	L12	90	A13	115	B4
16	G3	41	N5	66	L13	91	C11	116	A3
17	G1	42	L6	67	K12	92	B12	117	A2
18	H1	43	M6	68	J11	93	A12	118	C4
19	H2	44	N6	69	K13	94	C10	119	B3
20	H3	45	M7	70	J12	95	B11	120	A1
21	J1	46	L7	71	J13	96	A11		
22	J2	47	N7	72	H11	97	B10		
23	K1	48	N8	73	H12	98	C9		
24	J3	49	M8	74	H13	99	A10		
25	K2	50	L8	75	G12	100	B9		

BOND	PIN	NOTE
121	D4	NO CONNECTION

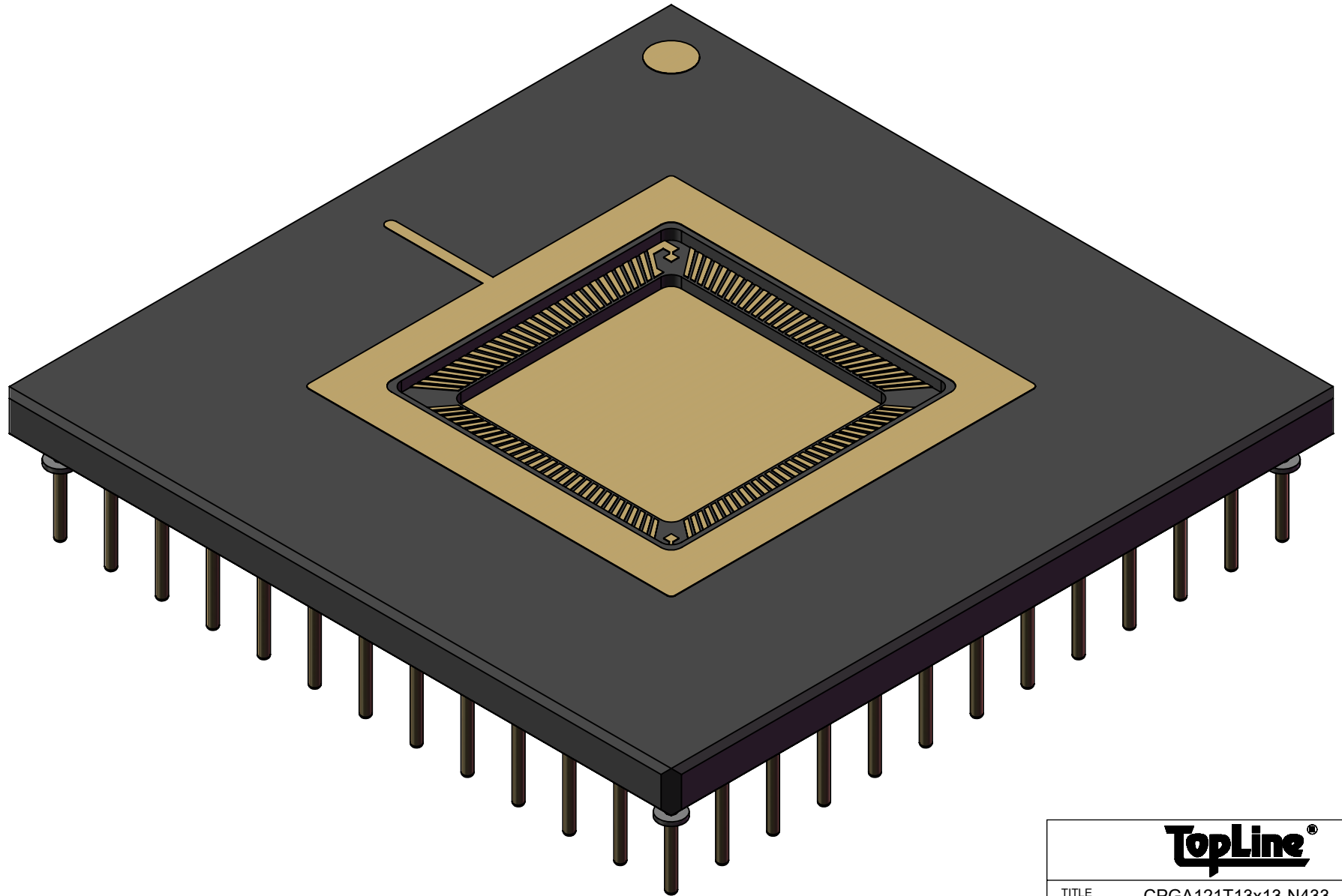
TopLine[®]

TITLE CPGA121T13x13-N433
CERAMIC PIN GRID ARRAY

SCALE 8:1	SIZE A	DRAWING NO. 161210	REV A
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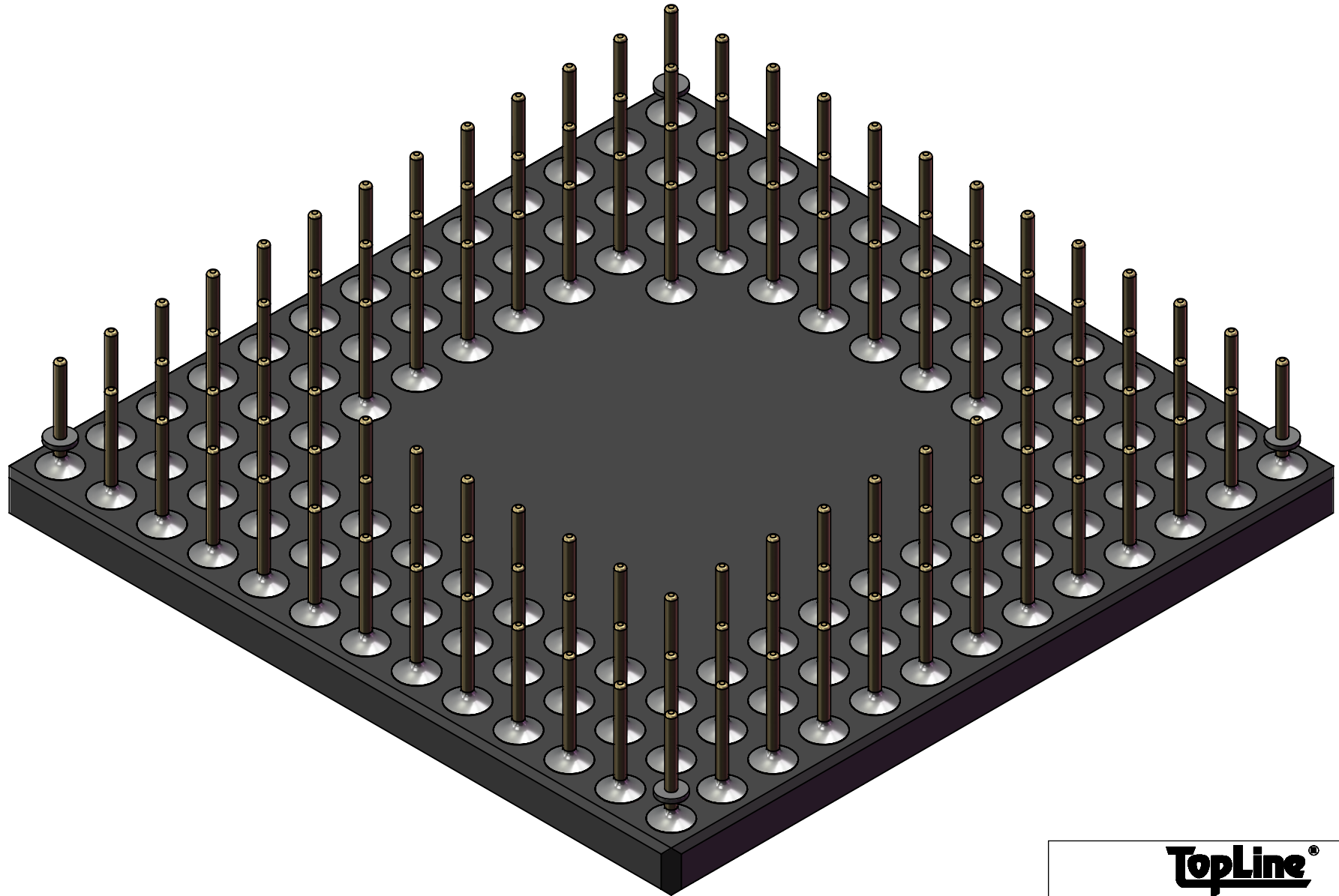
DO NOT SCALE DRAWING SHEET 4 OF 7

MODEL
SHOWN WITHOUT LID



TopLine[®]			
TITLE CPGA121T13x13-N433 CERAMIC PIN GRID ARRAY			
SCALE 5:1	SIZE A	DRAWING NO. 161210	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 7

**MODEL
BOTTOM**



TopLine®

TITLE CPGA121T13x13-N433
CERAMIC PIN GRID ARRAY

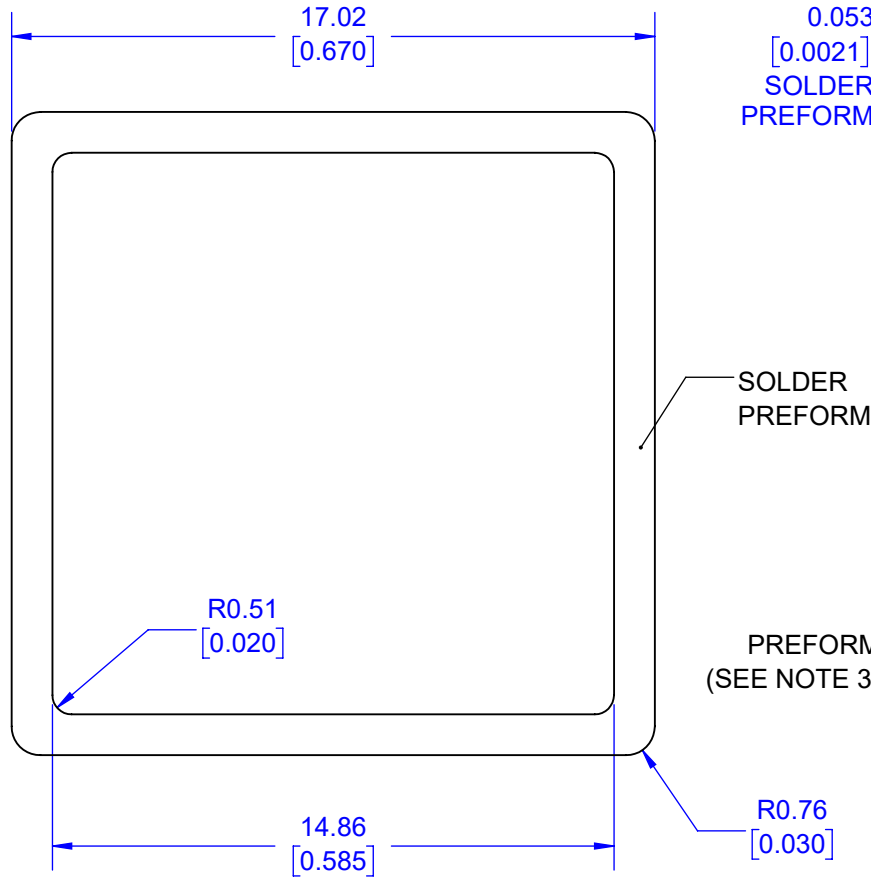
SCALE 5:1	SIZE A	DRAWING NO. 161210	REV A
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DO NOT SCALE DRAWING

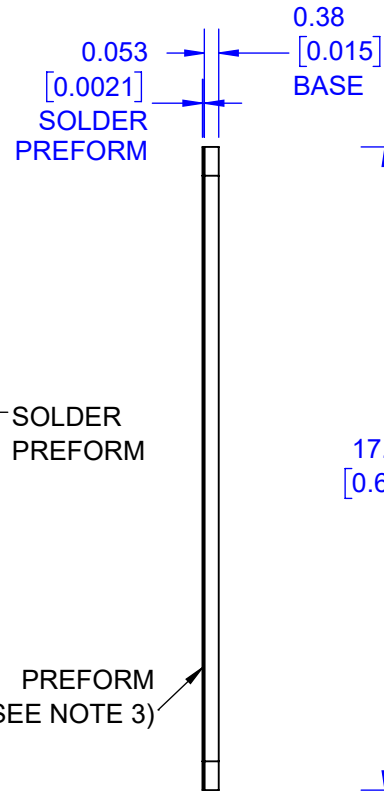
SHEET 6 OF 7

OPTIONAL COMBO LID

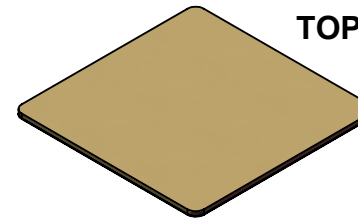
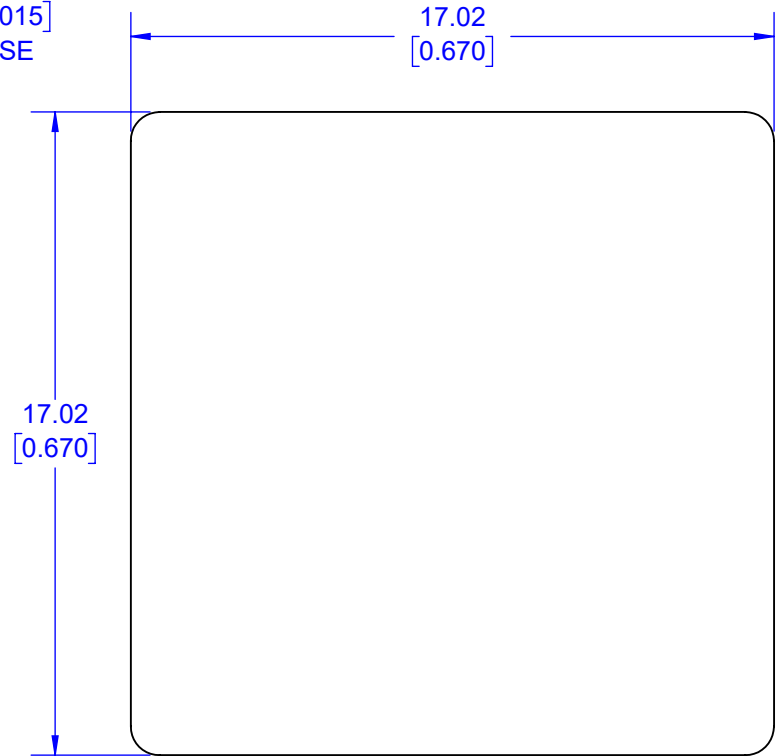
BOTTOM



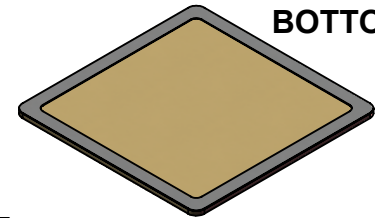
SIDE



COMBO LID



TOP



BOTTOM

MODEL

NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ± 1.0 Sn 20%.
4. FLATNESS: 1.0 MIL (25µm) MAXIMUM PER 0.5-INCH (12.7mm).

TopLine®

TITLE		CL-670SQ-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	170327	A
DO NOT SCALE DRAWING			SHEET 7 OF 7